

PRIMERGY RX300 S8

System configurator and order-information guide

March 2017

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Change report



Instructions

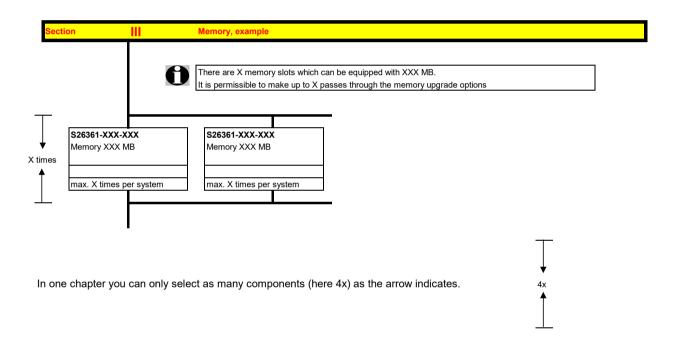
This document contains basic product and configuration information that will enable you to configure your system via PC-/System-Architect.

Only these tools will ensure a fast and proper configuration of your PRIMERGY server or your complete PRIMERGY Rack system.

You can configure your individual PRIMERGY server in order to adjust your specific requirements.

The System configurator is divided into several chapters that are identical to the current price list and PC-/SystemArchitect.

Please follow the lines. If there is a junction, you can choose which way or component you would like to take. Go through the configurator by following the lines from the top to the bottom.



Please note that there are information symbols which indicate necessary information.



For further information see:

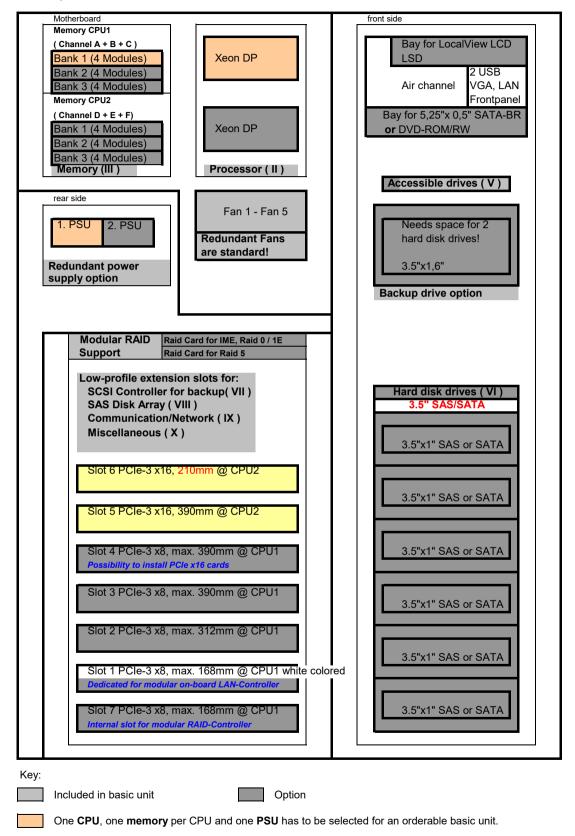
http://ts.fujitsu.com/products/standard_servers/inc (internet)

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Configuration diagram PRIMERGY RX300 S8

System unit (I)

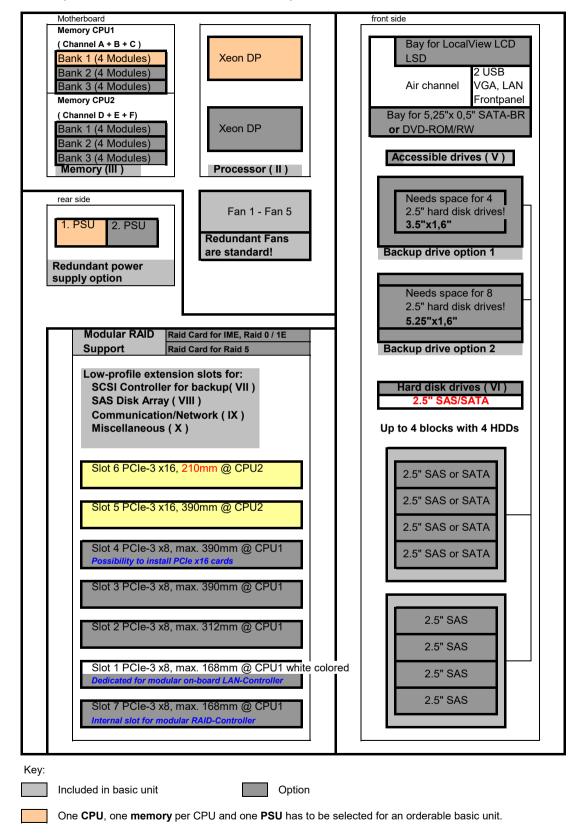
with up to 6x 3.5" Hard disk drives



Configuration diagram PRIMERGY RX300 S8

System unit (I)

with up to 4, 8, 12 or 16x 2.5" Hard disk drives or up to 4 or 8 PCle SSDs 2.5"



Section

Basic unit



System unit consisting of:

- * 2U Housing without power supply modules
- Basic units with:
- 2 Hot-Plug Power Supply Bays
- 5 Fans (full redundancy)
- 12 memory DIMMs per CPU (max 768GB) => Total 24 DIMMs (max 1536GB) for two CPU's
- * SAS Backplane for 6x 3.5" HD, SAS Backplanes for 4, 8, 12 or 16x 2.5" HD or PCIe Backplanes for 4 or 8 PCIe SSD with cable connection to on-board, modular RAID Controller

* Drives/Bays

- 6 bays 1" for hot plug 3.5" HD (1" high) or 4, 8, 12 or 16 bays for hot plug 2.5" HD
- 1 bay for 3.5" and 1.6" high Backup device, consumes 2 bays for 3.5" HD for basic unit 6x 3.5" HD not possible for basic unit with 12 or 16×2.5 " HD
- 1 bay for 5.25" and 1.6" high Backup device, not possible for basic unit 6x 3.5" HD for basic unit with 12 or 16 x 2,5" HD
- 1 bay SATA-CD- or DVD-ROM 0,5" height (option)
- 1 bay for opt. LocalView LC-Display
- * Integrated ServerView Diagnostics Technology (Diagnosis LED's) for indication of internal failed components

Systemboard D2939-B with:

* Up to two Xeon DP CPU's (Socket-R)

with 2 serial QPI links (Quick Path Interconnect) and four memory channels per CPU First CPU has to be selected for an orderable basic unit.

- * Chipset Intel® C600 Series (codenamed Patsburg)
- * 7 PCI slots: 2x PCIe-3 x16 (both slots are connected to CPU 2 and are useable with configured 2nd CPU only!)
 - 4x PCle-3 x8 (one notched to install x16 cards)
 - 1x PCIe-3 x8 (for internal modular RAID controller only)
- * 24 memory slots for max. 1536GB RAM DDR3 available
- Memory is divided into 12 DIMMs per CPU (4 channels with 3 slots per channel)

Possible max. configurations are:

16x 8GB UDIMM (dual rank modules) = 128GB

24x 16GB RDIMM (dual rank modules) = 384GB

24x 32GB LRDIMM (quad rank modules) = 768GB

24x 64GB LRDIMM (eight rank modules) = 1536GB

First Memory (one module) has to be selected for an orderable basic unit per CPU

- Memory upgrade is possible module wise
- Memory mirrroring is supported with 2 identical modules in channel A+B CPU 1 or D+E CPU 2
- Hot Spare Memory is supported with 3 identical modules in channel A+B+C CPU 1 or D+E+F CPU 2 $\,$
- SDDC (Chipkill) is supported for memory modules,
- * Dual Port 10/100/1000 x4 PCI Express* Gigabit Ethernet Intel LAN controller Powerville on-board
- * iRMC S4 (integrated Remote Management Controller) on-board server management controller with dedicated 10/100/1000 Service LAN-port and integrated graphics controller.

The Service LAN-port can be switched alternatively on standard Gbit LAN port 1

Graphics Controller integrated in iRMC S4 (integrated Remote Management Controller): 1600x1200x16bpp 60Hz, 1280x1024x16bpp 60Hz, 1024x768x32bpp 75Hz, 800x600x32bpp 85Hz, 640x480x32bpp 85Hz

 $(1280x1024x24bpp\ 60Hz\ only\ possible\ if\ local\ monitor\ or\ remote\ video\ redirection\ is\ off)$

Interfaces at the rear:

- * 1x RS-232-C (serial, 9 pins) (usable for BMC or OS or shared)
- * 1x VGA (15 pins)
- * 4x USB **2.0** (UHCI) with **480MBit/s**, no USB wakeup
- * 2x LAN RJ45, 1x Service-LAN RJ45

Interfaces on the front:

- * 2x USB **2.0** (UHCI) with **480MBit/s,** no USB wakeup
- * 1x VGA (15 pins) as an option
- * 1x Service-LAN RJ45 as an option

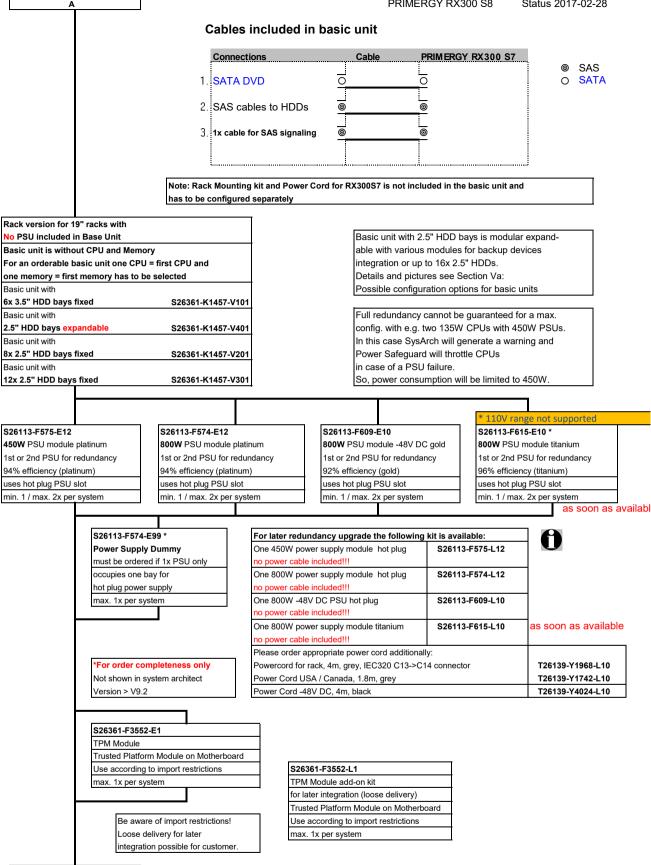
Interfaces internal:

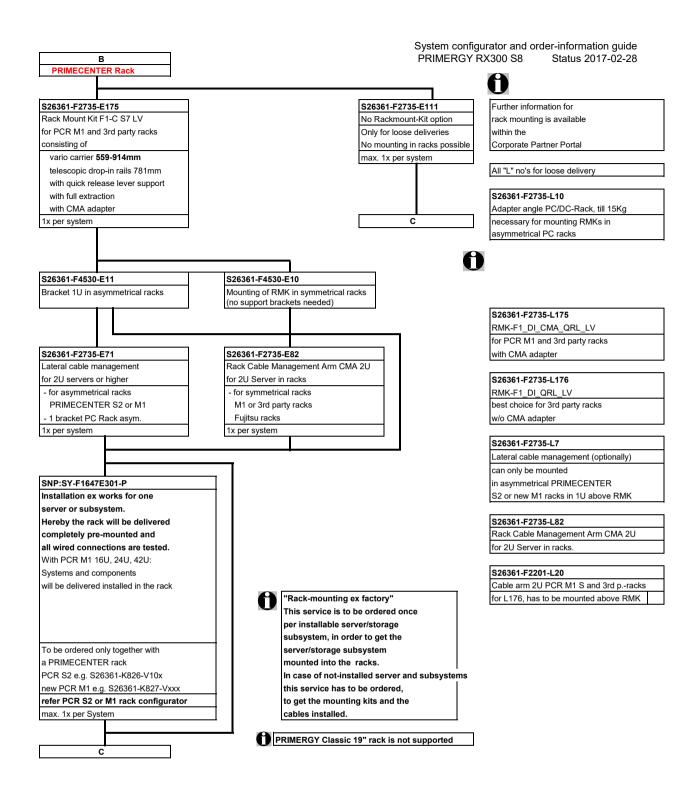
- * 1x released internal USB Interfaces for backup devices,
- * 1x USB 2.0 (UHCI) with 480MBit/s for dongle funcionality (uSSD memory), no USB wakeup
- * 1x SATA interface for DVD (only usable with 4x 2.5" HDD + DVD Option)
- * 4x SATA/SAS interface for 4 SATA/SAS HD`s or SAS Backup device
- * 2x USB 2.0 ports for internal USB redirection connected to BMC

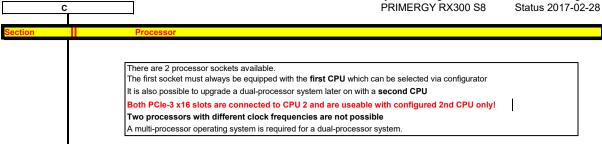
Software

* ServerView Suite Software package incl. ServerStart, ServerBooks, Management Software and Updates

* Documentation engl. (multilingual on CD)





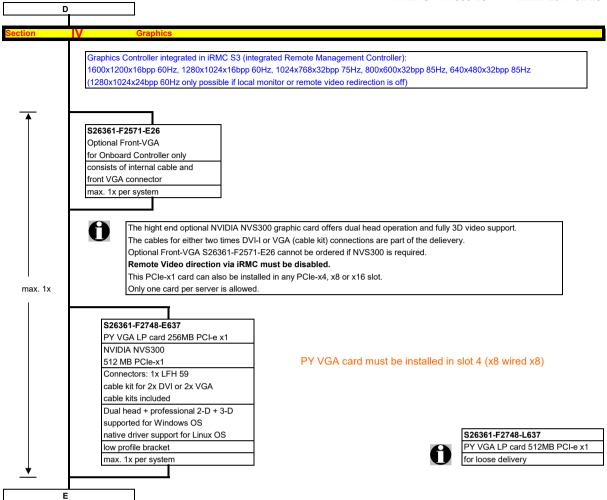


Max. two CPU`s can be selected per basic unit	
One of following CPU's has to be selected as first CPU	
for an orderable basic unit	
Optional second CPU has to be the same type like the first CPU	
Basic 4C CPU's	
- 1x 64-bit Intel Xeon (10MB Smart Cache)	
1333 MHz DDR3 Bus; 6,40 GT/s QPI Bus and passive heat sink	
occupies socket for one CPU	
Xeon E5-2603v2 4C/4T 1.80GHz 10MB 6.40GT/s 1333MHz 80W	S26361-F3788-E180
Xeon E5-2609v2 4C/4T 2.50GHz 10MB 6.40GT/s 1333MHz 80W	S26361-F3788-E250
Standard Turbo 6C/8C CPU's	
- 1x 64-bit Intel Xeon (15/20MB Smart Cache); Hyper-Threading (HT);	
1600 MHz DDR3 Bus; 7,20 GT/s QPI Bus and passive heat sink	
occupies socket for one CPU	
Xeon E5-2620v2 6C/12T 2.10GHz 15MB 7.20GT/s 1600MHz 80W	S26361-F3789-E210
Xeon E5-2630v2 6C/12T 2.60GHz 15MB 7.20GT/s 1600MHz 80W	S26361-F3789-E260
Xeon E5-2640v2 8C/16T 2.00GHz 20MB 7.20GT/s 1600MHz 95W	S26361-F3789-E200
Advanced Turbo+ 8C/10C CPU's	
- 1x 64-bit Intel Xeon (20/25MB Smart Cache); Hyper-Threading (HT);	
1866 MHz DDR3 Bus; 8,00 GT/s QPI Bus and passive heat sink	
occupies socket for one CPU	
Xeon E5-2650v2 8C/16T 2.60GHz 20MB 8.00GT/s 1866MHz 95W	S26361-F3790-E260
Xeon E5-2660v2 10C/20T 2.20GHz 25MB 8.00GT/s 1866MHz 95W	S26361-F3790-E220
Xeon E5-2670v2 10C/20T 2.50GHz 25MB 8.00GT/s 1866MHz 115W	S26361-F3790-E250
Xeon E5-2680v2 10C/20T 2.80GHz 25MB 8.00GT/s 1866MHz 115W	S26361-F3790-E280
Xeon E5-2690v2 10C/20T 3.00GHz 25MB 8.00GT/s 1866MHz 130W	S26361-F3790-E300
Segment Optimized CPU's	
- 1x 64-bit Intel Xeon (15/25/30MB Smart Cache); Hyper-Threading (HT);	
1866 MHz DDR3 Bus; 8,00 GT/s QPI Bus and passive heat sink	
occupies socket for one CPU	
Xeon E5-2637v2 4C/8T 3.50GHz 15MB 8.00GT/s 1866MHz 130W	S26361-F3791-E350
Xeon E5-2643v2 6C/12T 3.50GHz 25MB 8.00GT/s 1866MHz 130W	S26361-F3791-E330
Xeon E5-2667v2 8C/16T 3.30GHz 25MB 8.00GT/s 1866MHz 130W	S26361-F3791-E300
Xeon E5-2695v2 12C/24T 2.40GHz 30MB 8.00GT/s 1866MHz 115W	S26361-F3791-E240
Xeon E5-2697v2 12C/24T 2.70GHz 30MB 8.00GT/s 1866MHz 130W	S26361-F3791-E270
Low Power 6C/10C CPU's	
- 1x 64-bit Intel Xeon (15/25MB Smart Cache); Hyper-Threading (HT);	
1600 MHz DDR3 Bus; 7,20/8,00 GT/s QPI Bus and passive heat sink	
occupies socket for one CPU	
Xeon E5-2630Lv2 6C/12T 2.40GHz 15MB 7.20GT/s 1600MHz 60W	S26361-F3792-E240
Xeon E5-2650Lv2 10C/20T 1.70GHz 25MB 8.00GT/s 1600MHz 70W	S26361-F3792-E170



- Max. DDR3 Bus Speed depends on:
 max. DDR3 Bus Speed from the CPU and
- max. DDR3 Memory Speed and
- max. memory modules on one memory channel For CPUs which do not offer 1866 MHz support, (Basic, Standard & Low Power class),

System Architect will not offer memory modules supporting this frequency.



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Section III Memory



- There are 12 memory slots per CPU for max.

768GB LRDIMM (12x 64GB 8R)

192GB RDIMM (12x 16GB 2R)

64GB UDIMM (8x 8GB) on special Release only

=> max. 1.536GB for two CPU's (768GB per CPU), using LRDIMM

- The memory area is divided into 4 channels per CPU with 3 slots per channel

- Slot 1 of each channel belongs to memory bank 1, the slot 2 belongs to memory bank 2, slot 3 belongs to memory bank 3

Registered, LR DIMMs and unbuffered memory modules can be selected

No mix of registered, load reduced and unbuffered modules allowed.

Memory can be operated at 1.5V or 1.35V, even if the modules are of low voltage type.

Memory operating voltage can be set within BIOS (1.5V is default setting for max. speed).

In a single DIMM per channel configuration, following frequencies are supported:

- 1.5V 1866MHz max (depending on CPU)
- 1.35V 1600MHz max (depending on CPU, up to two LRDIMM per channel)
- 1.35V 1333MHz max (up to two UDIMM or RDIMM per channel)

In a 3 DIMMs per channel configuration, memory will operate at 1.35V or 1.5V (no UDIMM allowed).

SSD (Chipkill) is supported for registered / load reduced x4 organized memory modules only.

1.) In the "Independent Channel Mode" is following configuration possible

Channels can be populated in any order in Independent Channel Mode. All four channels may be populated in any order and have no matching requirements. All channels must run at the same interface frequency but individual channels may run at different DIMM timings (RAS latency, CAS latency, and so forth)

No mix of registered, load reduced and unbuffered modules allowed.

2.) "Rank Sparing Mode" configuration

- Within a memory channel, one rank is a spare of the other ranks.

The Spare Rank is held in reserve and is not available as system memory

For the effective memory capacity, please refer to the spreadsheet below.

The BIOS is set to the rank sparing setting.

Minimum configuration is: 2x 1R, 2x 2R or 1x4R DDR3 module per channel

This mode is not supported by unbuffered memory modules

3.) "Performance Mode" configuration

- In this configuration, the memory module population ex factory is spread across all channels.

The BIOS is set to the max. performance for memory.

Minimum configuration is: 4x identical modules

4.) In the "Mirrored Channel Mode" is following configuration possible

- Each memory bank can optionally be equipped with 4x registered or load reduced or unbuffered DDR3 modules

In each memory bank channel A and B / C and D of CPU 1 or channel E and F / G and H of CPU 2 have to be equipped with identical modules for mirrored channel mode.

In channel B / D is always the mirrored memory of channel A / B of CPU 1

In channel F / H is always the mirrored memory of channel E / G of CPU 2

Minimum configuration is: 4x identical modules

This mode is not supported by unbuffered memory modules

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S26361-F3694-E10 Independent Mode

Independent Channel Mode allows all channels to be populated in any order. No specific Memory RAS features are defined

Requires min 1 memory Module per CPU

S26361-F3694-E1 Rank Sparing Mode Installation

BIOS Setup factory preinstalled to this mode. One Rank is spare of other ranks on the same channel. Spare Rank is not shown in System Memory. For effective capacity within a channel. please have a look below.

Supported for RDIMM / LRDIMM only.

1x per CPU Requires min 2x 1R/2R or 1x 4R modules per CPU

S26361-F3694-E2 Performance Mode Installation

BIOS Setup factory preinstalled for max. Performance, LV memory might be set to 1.5V operation. Four identical memory modules

will be equipped in one memory bank to achieve highest memory performance. All four modules are active and full capacity can be used.

Multiple of 4 identical modules to be configured per CPU

S26361-F3694-E3 Mirrored Channel Mode Installation

BIOS Setup factory preinstalled to this mode. Four identical memory modules are always equipped in one memory bank to use the

Mirrored channel Mode. Only two modules contain active data, the remain two modules contain mirrored data

Supported for RDIMM / LRDIMM only.

Multiple of 4 identical modules to be configured per CPU



Effe	Effective Memory capacity / Rank Sparing Mode, 1 Channel populated								
		RD	IMM	LRD	MMI				
	4GB 1R	8GB 1R	8GB 2R	16GB 2R	32GB 4R	64GB 8R	•		
1DPC	na	na	na	na	24GB	48GB			
2DPC	4GB	8GB	12GB	28GB	56GB	112GB			
3DPC	8GB	16GB	20GB	44GB	80GB	160GB			



Minimum one memory module or order code per CPU = first memory

Note 1.)

Unbuffered Memory (UDIMM) no SDDC (chipkill) support

one DDR3 unbuffered ECC mem. Module, 1.35V

Choose up to 8 order codes per CPU

BGB (1x8GB) 2Rx8 L DDR3-1600 U ECC S26361-F3807-E515

Registered Memory (RDIMM) with SDDC (chipkill) support

one DDR3 registered ECC mem. Module, 1.35V

1333MHz supported with up to 2DPC (8 modules/CPU) and 1.35V

1600MHz supported with up to 2DPC (8 modules/CPU) and 1.5V

Choose up to 12 order codes per CPU

4GB (1x4GB) 1Rx4 L DDR3-1600 R ECC	S26361-F3781-E514
8GB (1x8GB) 1Rx4 L DDR3-1600 R ECC	S26361-F3781-E515
16GB (1x16GB) 2Rx4 L DDR3-1600 R ECC	S26361-F3781-E516

Registered Memory (RDIMM) with SDDC (chipkill) support

- one DDR3 registered ECC mem. Module, 1.5V

1866MHz supported with up to 2DPC (8 modules/CPU)

Choose up to 12 order codes per CPU

16GB (1x16GB) 2Rx4 DDR3-1866 R ECC S26361-F3793-E516

Registered Memory (RDIMM) no SDDC (chipkill) support

one DDR3 registered ECC mem. Module, 1.5V
 No mix with any other types of memory modules possible

1866MHz supported with up to 2DPC (8 modules/CPU)

Choose up to 12 order codes per CPU

8GB (1x8GB) 2Rx8 DDR3-1866 R ECC S26361-F3793-E515

Load Reduced Memory (LRDIMM) with SDDC (chipkill) support

- one DDR3 load reduced ECC mem. Module, 1.35V

Choose up to 12 order codes per CPU

Load Reduced Memory (LRDIMM) with SDDC (chipkill) support

one DDR3 load reduced ECC mem. Module, 1.5V

1866MHz supported with up to 2DPC (8 modules/CPU)

Choose up to 12 order codes per CPU

32GB (1x32GB) 4Rx4 DDR3-1866 LR ECC S26361-F3848-E517

special release only



Note 1)

Max. DDR3 memory speed depends on the memory configuration (No of mem modules per channel) as well as on the CPU type. The memory channel with the lowest speed defines the speed of all CPU channels in the system, also for the channels of the second CPU if configured.

For real memory speed (depending on memory type / population), please check the spreadsheet "Memory speed" below

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Note 2)

Mix of memory modules is only possible within the same group

8/12x per

CPU, max.

2/3 modules

per channel

Memory Configuration PRIMERGY RX300 S8

Each CPU offers 12 Slots for DDR3 Memory Modules organised in 3 Banks and 4 Channels.

If you need more than 12 Slots you have to configure the 2nd CPU.

Depending on the amount of memory configured you can decide between 4 basic modes of operation (see explanation below).

There are 3 different kinds of DDR3 Memory Modules available: UDIMM / RDIMM and LRDIMM UDIMM / RDIMM / LRDIMM offer different functionality. Mix of UDIMM / RDIMM / LRDIMM is not alloved.

If 1.5V and 1.35V DIMMs are mixed, the DIMMs will run at 1.5V

Mode	Configuration	UDIMM	RDIMM	RDIMM	Application
		OBIIIII	T(Dillill)	LRDIMM	
		x8	х8	x4	
SDDC (chipkill) support	any	no	no	yes	detect multi-bit errors
Independant Channel	1, 2 or 3 Modules per Bank	yes	yes	yes	offers max. flexibility, upgradeability, capacity
Mode					use UDIMM modules for lowest cost
Mirrored Channel Mode *)	4 identical Modules / Bank	no	no	yes	offers maximum security
Performance Mode	4 identical Modules / Bank	yes	yes	yes	offers maximum performance and capacity
Rank Sparing Mode *)	min. 2 Ranks / Channel	no	no	yes	balances security and capacity

^{*)} For the delivery ex works the system will be prepared with dedicated BIOS setting.

Capacity	Configuration	UDIMM	RDIMM	LRDIMM	Notes
Min. Memory per CPU	1 Module / CPU	1x4GB	1x4GB	1x32GB	with one CPU
Max. Memory per CPU	8/12 Modules / CPU	8x4GB	12x16GB	12x64GB	with one CPU
Max. Memory per System	16/24 Modules / System	64GB	384GB	1536GB	if second CPU is configured

Memory-Speed:

Max. DDR3 memory speed depends on the memory configuration on one memory channel and the speed of the CPU The memory channel with the lowest speed defines the speed of all CPU channels in the system

Mem. Speed provided by CPU	Real maximum memory-bus speed depending on CPU type, memory configuration (DPC) and voltage setting (BIOS)																	
	UDIMM 1866MHz			RDIMM 1866MHz					LRDIMM 4R 1866MHz									
Voltage setting (BIOS)	1.5√	/ [defa	ault]		1.35V	/	1.5V [default] 1.35V				/	1.5V [default] 1.35V				/		
	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3
	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC
CPU with 1866MHz DDR3 Bus	1866	1600	-	1333	1333	-	1866	1866	1066	1333	1333	800	1866	1866	1066	1600	1600	1066
CPU with 1600MHz DDR3 Bus	1600	1600	-	1333	1333	-	1600	1600	1066	1333	1333	800	1600	1600	1066	1600	1600	1066
CPU with 1333MHz DDR3 Bus	3 Bus 1333 1333 - 1333 1		1333	-	1333	1333	1066	1333	1333	800	1333	1333	1066	1333	1333	1066		

1R - Single Rank 4R - Quad Rank 2R - Dual Rank 8R - Eight Rank

1DPC = 1 DIMM per Channel 2DPC = 2 DIMM per Channel 3DPC = 3 DIMM per Channel

Configuration hints:

- The memory sockets on the systemboard offer a color coding:

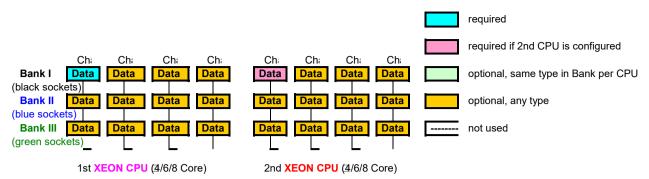
Bank I black sockets
Bank II blue sockets
Bank III green sockets

- A so called Bank consits of 1 memory module on every Channel available on one CPU (examples see below)

Bank I on CPU 1/2
Bank II on CPU 1/2
Bank III on CPU 1/2
Bank III

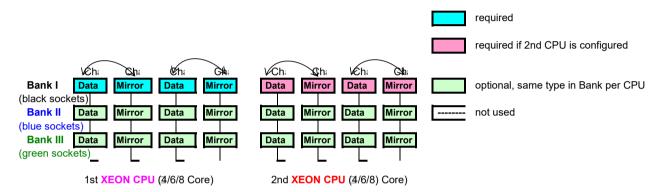
- See below and next page for a detailed descriptions of the memory configuration supported.

1. Independent Channel Mode



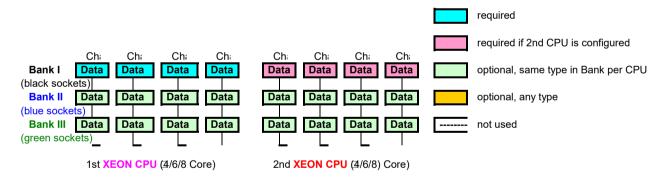
Independent Channel Mode allows all channels to be populated in any order Can run with differently rated DIMMs and use the settings of the slowest DIMM installed in the system

2. Mirrored Channel Mode



Mirrored Channel Mode requires identical modules on channel A,B, C, D (1st CPU) or channel E, F, G and H (2nd CPU) 50% of the capacity is used for the mirror => the available memory for applications is only half of the installed memory If this mode is used, a multiple of 4 identical modules has to be ordered.

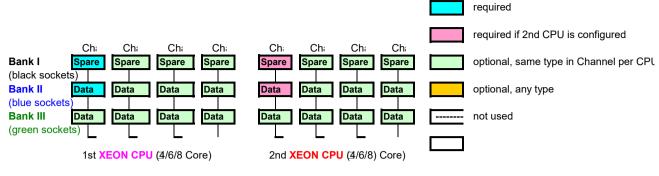
3. Performance Channel Mode



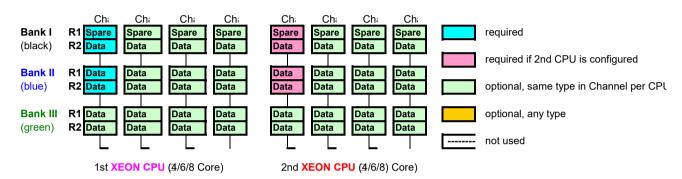
Performance Channel Mode requires identical modules on all channels of each Bank per CPU. If this mode is used, a multiple of 4 identical modules has to be ordered.

4. Rank Sparing Mode

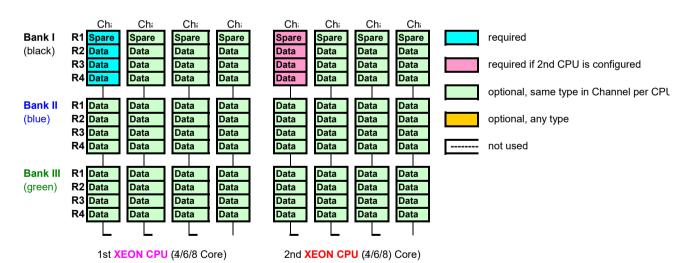
1-Rank Memory modules (RDIMM)



2-Rank Memory modules (RDIMM)



4-Rank Memory modules (LRDIMM)

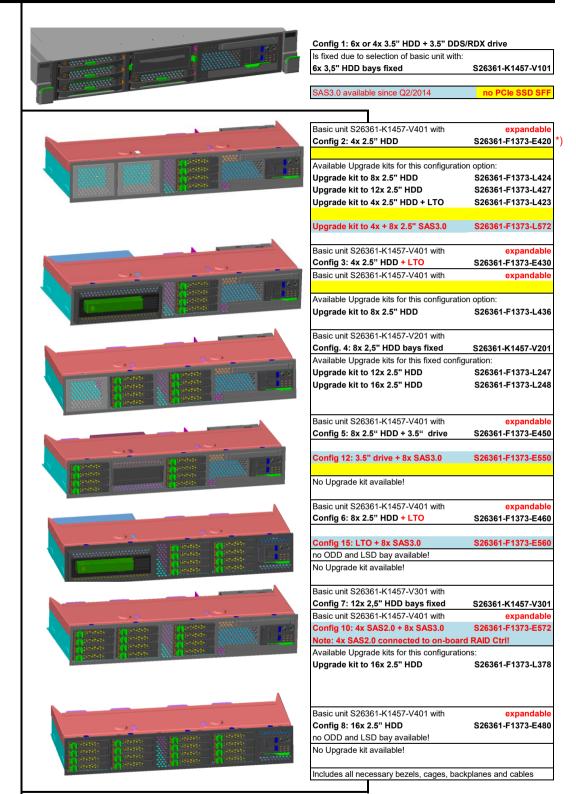


Rank Sparing Mode requires identical modules (same capacity and technology) within the same channel. The available memory for applications will vary depending on configuration. Please refer to the spreadsheet above "Effective Memory capacity with active Rank Sparing Mode". Population rule for Rank sparing mode is to achieve max. available memory, e.g. 6 DIMMs will be spread across two channels, each with 3DPC

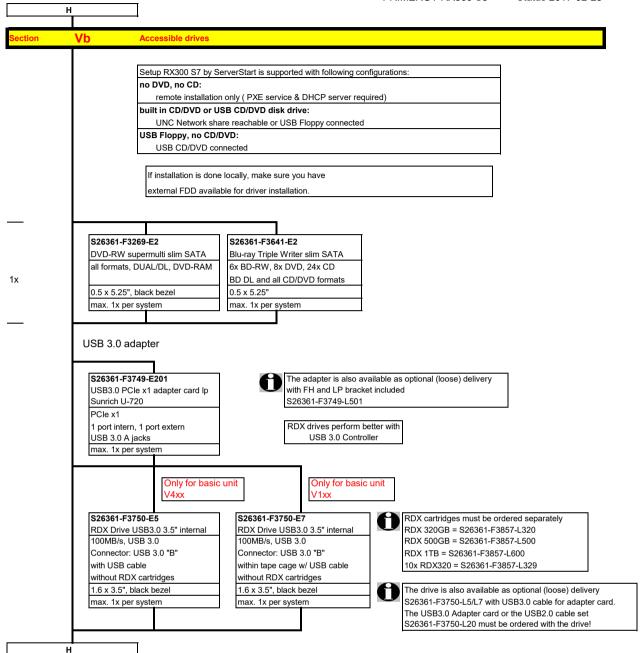
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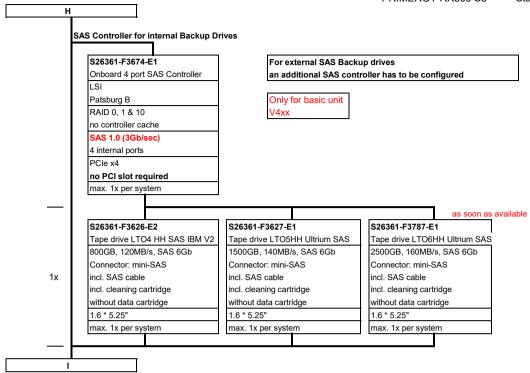
Section

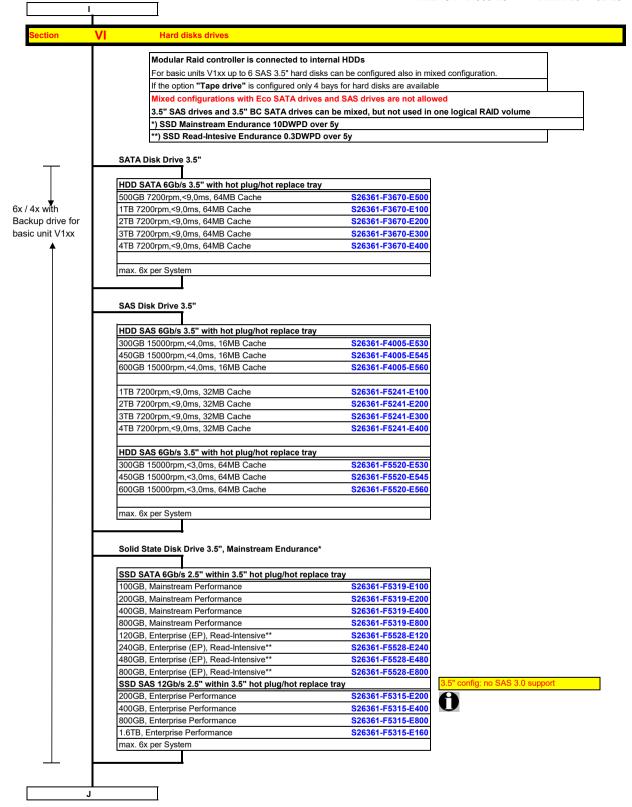
ossible configuration options for basic units

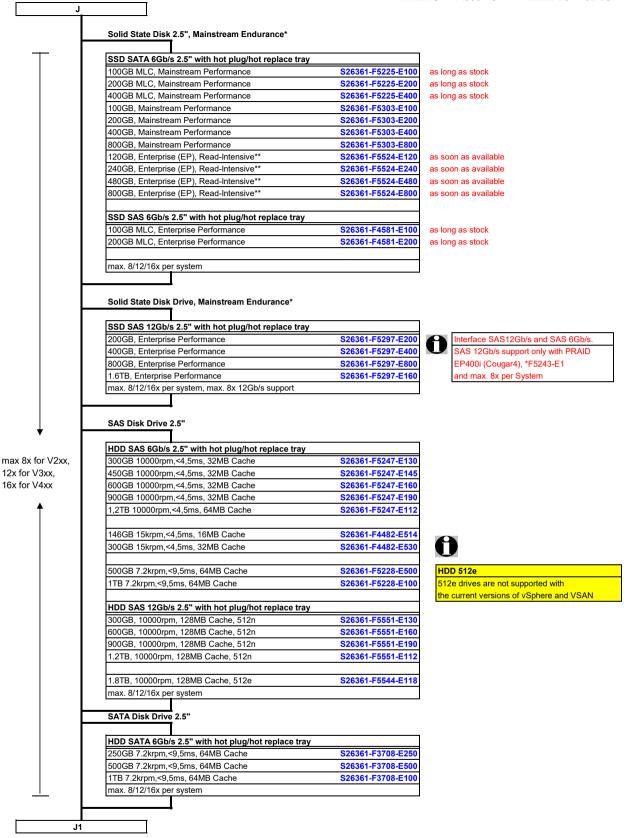


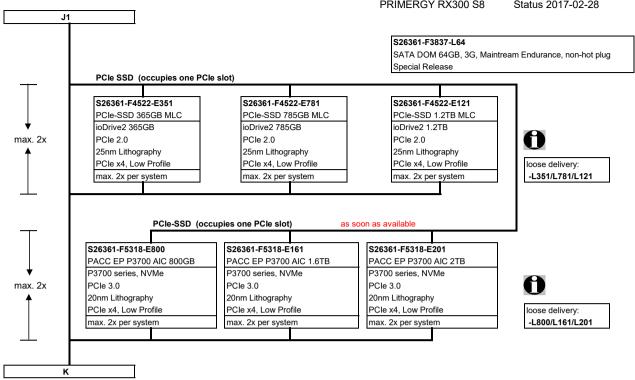
*) these are the only noHDD/SSD configuration opportunity without needed RAID controller

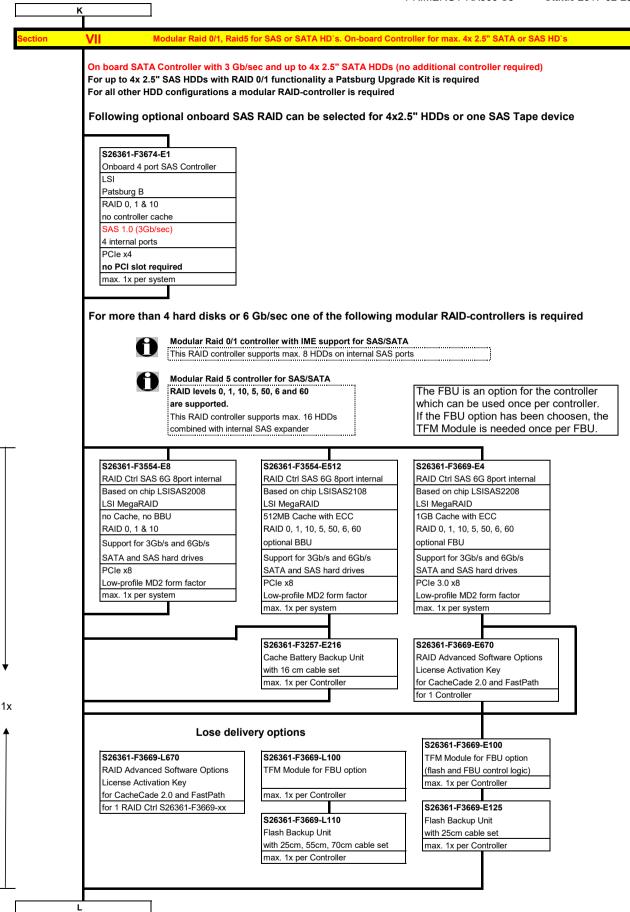


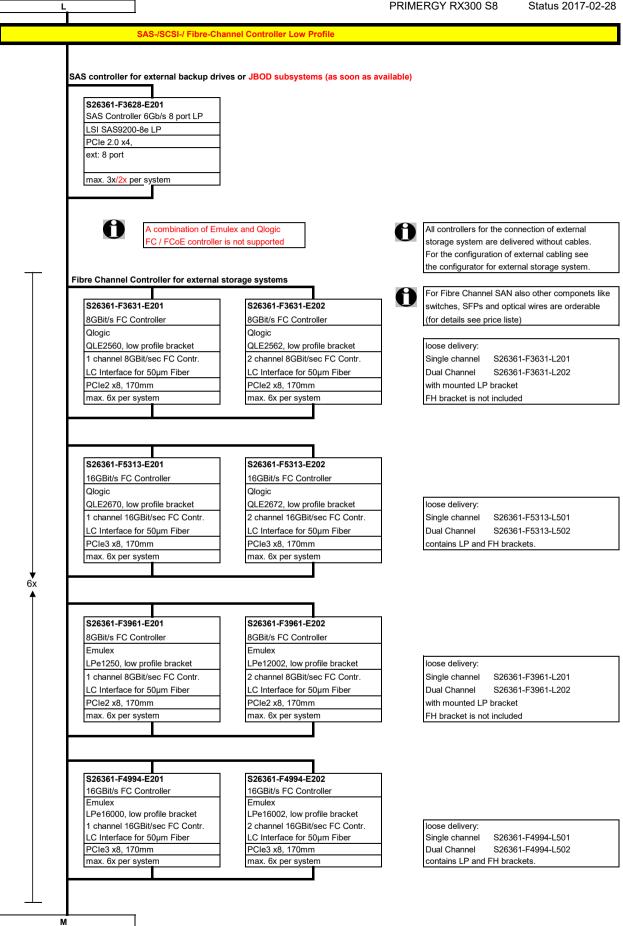


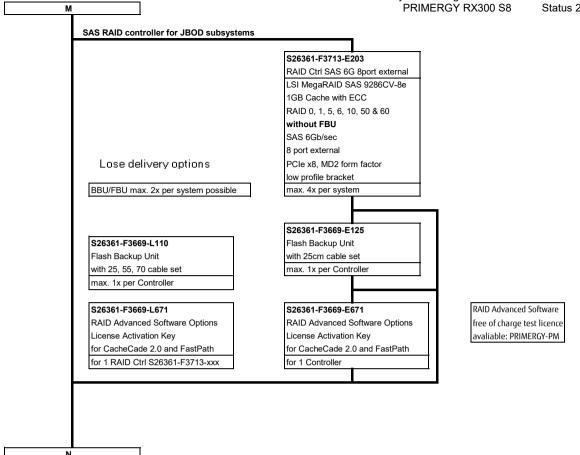


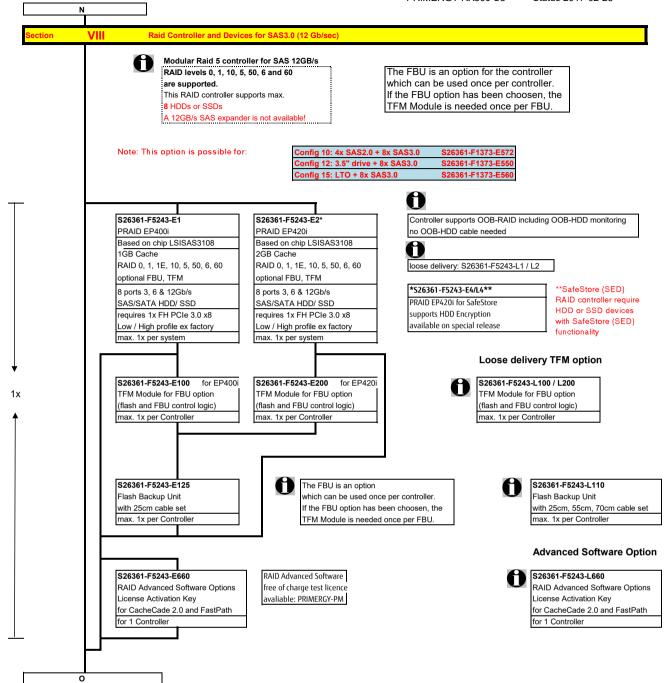


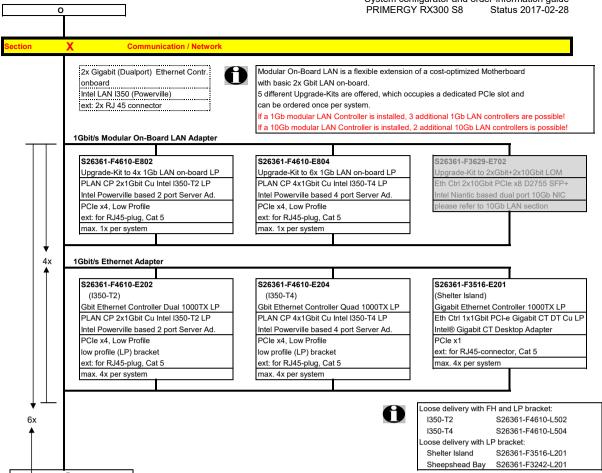


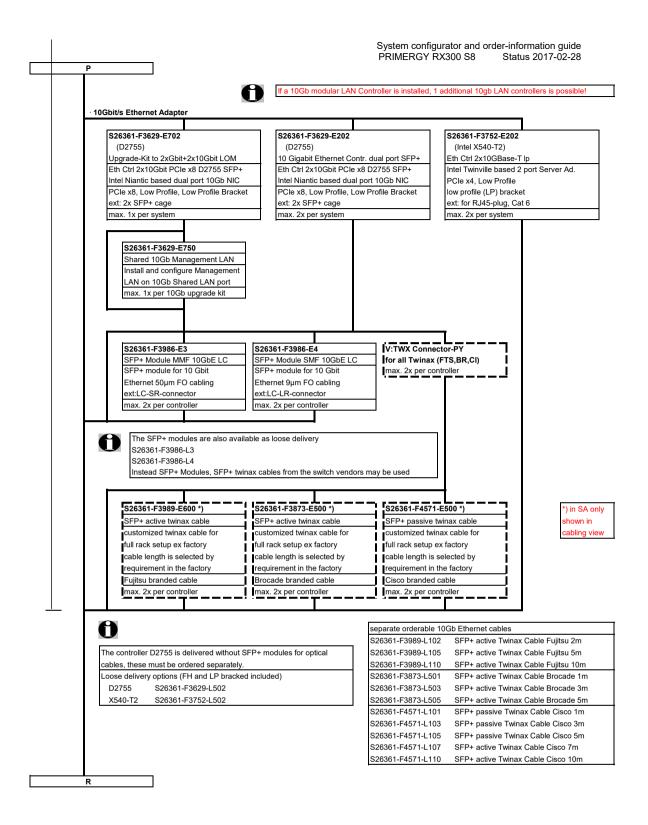


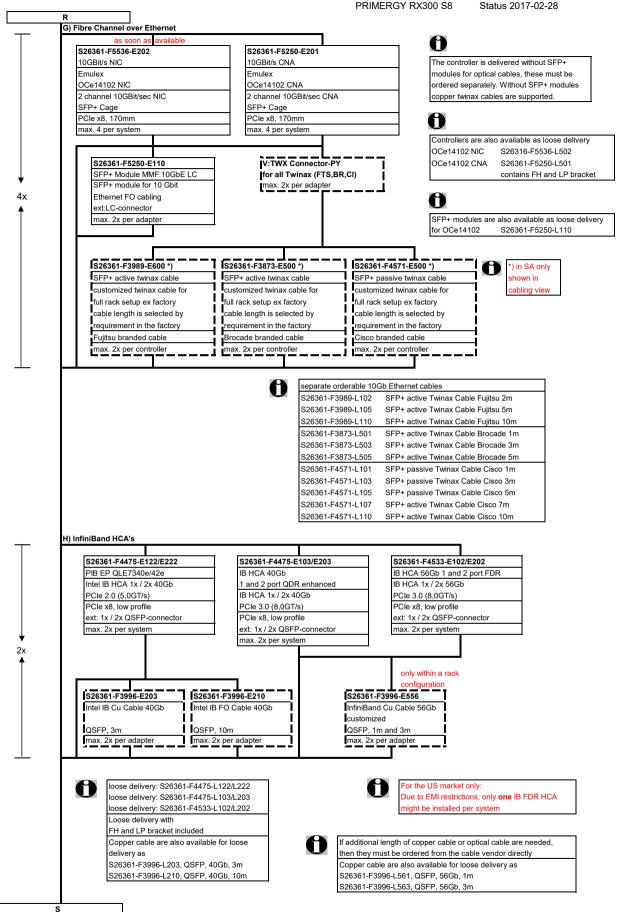


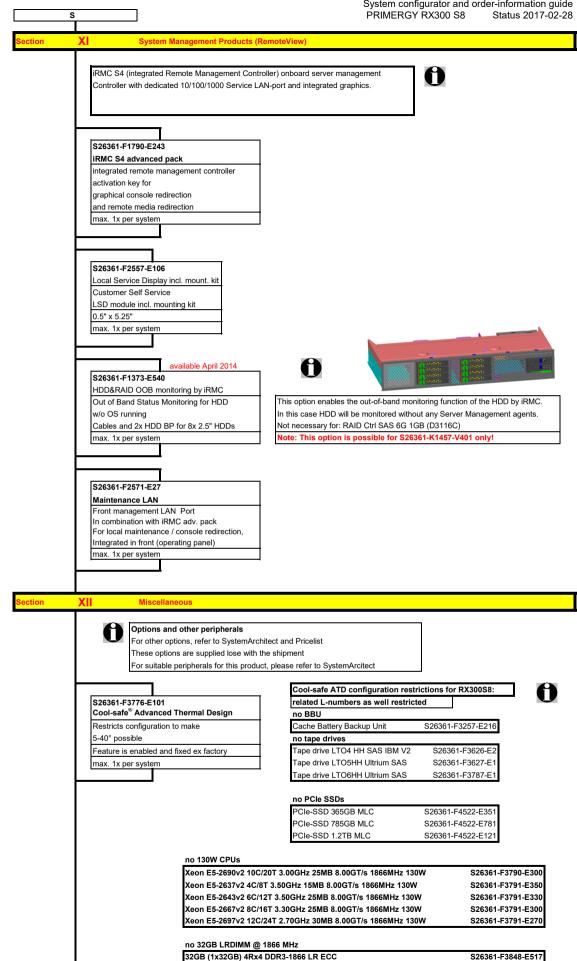


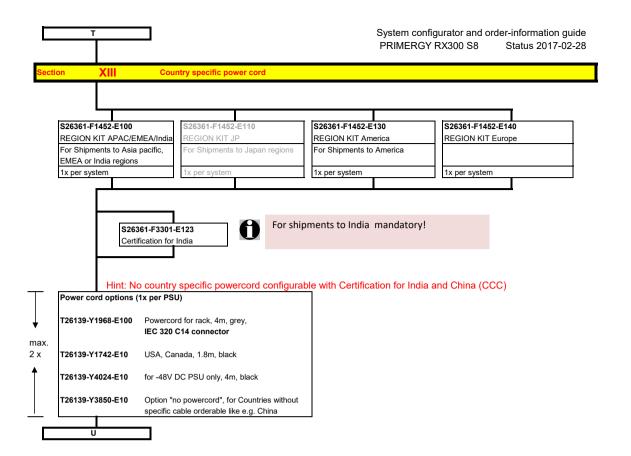


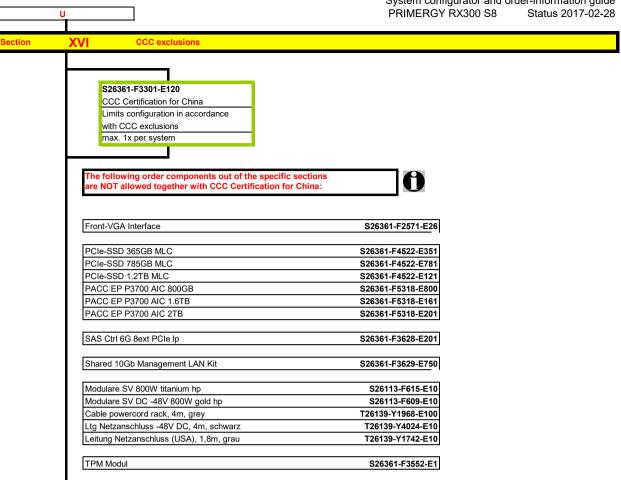












End PRIMERGY RX300 S8

Change Report

Date	Order number	Changes
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2017-02-09	S26361-F5243-E4/L4	comment added
2016-09-27	S26361-F2735-L10	corrected from 50kg to 15kg
2016-06-02	S26361-F5243-E4/L4	added
2016-05-10	S26361-F3669-E671/L671	added
2016-05-10	S26361-F3669-E670/L670	added
2016-05-10	S26361-F3669-E661/L661	removed
2016-05-10	S26361-F3669-E660/L660	removed
2016-03-21	S26361-F1452-E140	added region kit europe
2016-03-14	T26139-Y1742-E10	changed color to black
2015-10-01	S26361-F5243-E660	changed comment for FastPath and CacheCade
2015-07-22		RAID controller updated
2015-07-21	S26361-F5520-E*	Added 2.5" SAS 12G 10K 512n HDDs
2015-02-27	S26361-F5520-E*	Added 2.5" SAS 6G 15K HDD up to 600GB within 3.5" Carrier
2014-11-28		2.5" & 3.5" Read-Intensive SATA SSDs added
2014-10-20	S26361-F5536-E2	added Emulex OCe14012 dual channel 10Gb NIC
2014-08-04	S26361-F5313-xxx	16Gb Qlogic added
2014-07-03	S26361-F5315-E*	Added 3.5" SAS 12G SSDs
2014-07-02	S26361-F3848-E517	No ATD functionality with 32GB LRDIMM @ 1866 MHz
2014-06-30	S26361-F3301-E123	Added certification for India
2014-06-16	S26361-F3740-xxx	EOL
2014-06-16	S26361-F3739-xxx	EOL
2014-06-16	S26361-F3242-E201 / -L201	EOL
2014-06-10	S26361-F5319-E*	Added 3.5" SATA 6G SSDs
2014-05-19	S26361-F3848-E517	Added 32 GB LRDIMM 1866 MHz
2014-05-06	S26361-F53250	new CNA OCe14102 added
2014-05-02		PCIe SSD SFF options removed
2014-04-03	S26361-F3776-E101	Cool-safe ATD restriction changed - 32GB and 64GB LRDIMM no more restricted
2014-03-18		SAS3.0 RAID Ctrl updated
2014-03-17	S26361-F3739-E201	phase out
2014-03-17	S26361-F3740-E201	phase out
2014-03-17	S26361-F3610-E202	EOL
2014-03-05	S26361-F1373-E540	HDD&RAID OOB monitoring by iRMC added
2014-01-30	S26361-F5303-*	New SATA SSDs added.
2014-01-30	S26361-F5297-*	New SAS 12G SSDs added.
2013-12-12	S26361-F3554-E8	restricted for ATD
2013-11-29	S26361-F3837-L64	SATA DOM (Disk on module) added
2013-11-27	S26361-F3301-E120	Restrictions CCC Certification for China updated
2013-10-28		SSD support with On-Board controller.
2013-10-28		restriction for 2.5" BC-SAS HDD with "*F3554-E8" removed.
2013-10-18	optional USB Comps	no longer available
2013-10-16	S26361-F4610-E202 / -E204	added new 1Gb NICs from Intel
2013-10-09	S26113-F615-E10	add comment "110V range not supported"
2013-10-08		restrictions for Cool-safe ATD added
2013-09-19	C0C0C4 FE047 F440	Memory hint on CPU page extended HDD 1.2TB SAS 10K added.
2013-09-13 2013-09-03	S26361-F5247-E112	CMA not longer a must component
	RMK	First Release
2013-09-01		FIRST Release
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